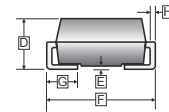
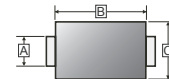


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- High Current Capability
- Extremely Low Thermal Resistance
- For Surface Mount Application
- Higher Temp Soldering : 250°C for 10 Seconds at Terminals
- Low Reverse Current

SMB (DO-214AA)



MECHANICAL DATA

- Case: Molded Plastic
- Epoxy: UL 94V-0 Rate Flame Retardant
- Lead: Axial Leads, Solderable per MIL-STD-202 Method 208 Guaranteed
- Polarity: Color Band Denotes Cathode End
- Mounting Position: Any

| REF. | Millimeter | | REF. | Millimeter | |
|------|------------|------|------|------------|-------|
| | Min. | Max. | | Min. | Max. |
| A | 1.91 | 2.20 | E | - | 0.203 |
| B | 4.06 | 4.70 | F | 5.08 | 5.59 |
| C | 3.30 | 3.94 | G | 0.76 | 1.52 |
| D | 2.13 | 2.44 | H | 0.15 | 0.305 |

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

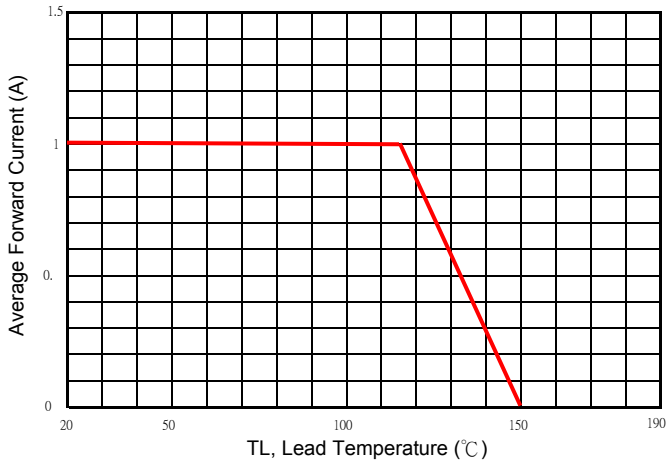
| TYPE NUMBER | SYMBOL | SM1150B | UNITS |
|---|-----------------------------|---------|------------------------|
| Peak Repetitive Peak reverse voltage | V_{RRM} | 150 | V |
| Working Peak Reverse Voltage | V_{RWM} | | |
| Maximum DC Blocking Voltage | V_R | | |
| Average Forward Current @ $T_J = 25^\circ\text{C}$ | $I_{F(AV)}$ | 1 | A |
| Peak Forward Current @ 8.3 ms Half Sine | I_{FSM} | 30 | A |
| Maximum Instantaneous Forward Voltage $V_F @ I_{FM} = 1.0 \text{ A}$ | @ $T_J = 25^\circ\text{C}$ | 0.85 | V |
| | @ $T_J = 125^\circ\text{C}$ | 0.67 | |
| Maximum Reverse Current At V_{RRM} Voltage (Note 3) | @ $T_J = 25^\circ\text{C}$ | 0.1 | mA |
| | @ $T_J = 125^\circ\text{C}$ | 5 | |
| Typical Junction Capacitance (Note 1) | C_J | 65 | pF |
| Typical Thermal Resistance Note 2) | $R_{\theta JL}$ | 25 | $^\circ\text{C/W}$ |
| Voltage Rate of Change (Rated V_R) | dv/dt | 10000 | $\text{V}/\mu\text{s}$ |
| Operating Temperature Range | T_J | -50~150 | $^\circ\text{C}$ |
| Storage temperature | T_{STG} | -65~150 | $^\circ\text{C}$ |

NOTES:

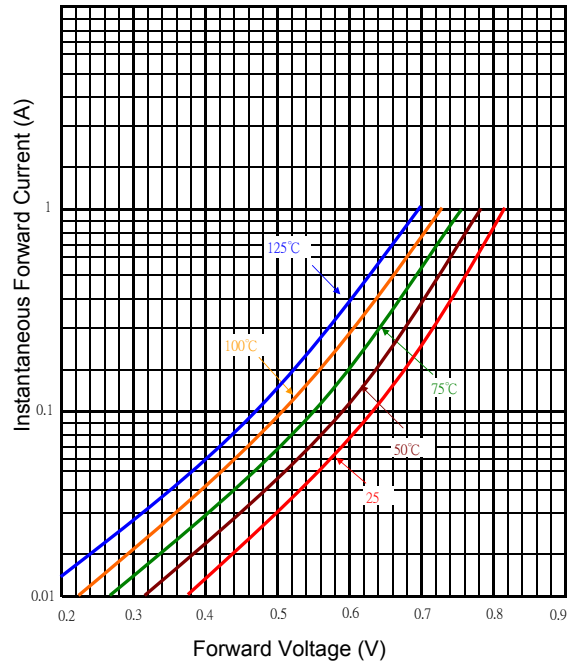
1. Measured at 1MHz and applied reverse voltage of 0 V D.C.
2. Thermal Resistance Junction to Lead.
3. Pulse test: 300us pulse width, 1% duty cycle

RATINGS AND CHARACTERISTIC CURVES

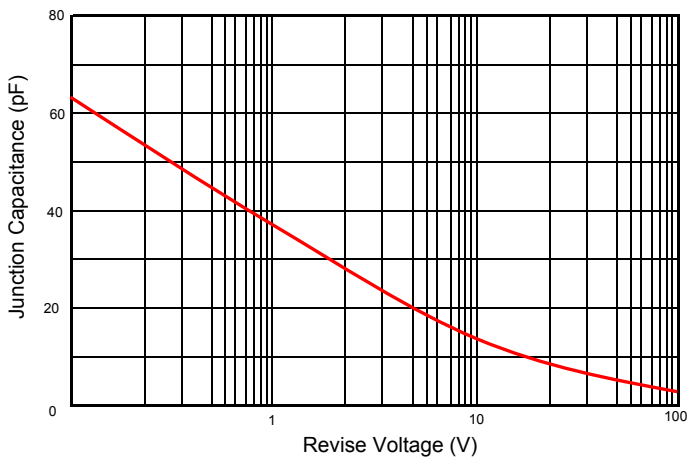
Typical Forward Current Derating Curve



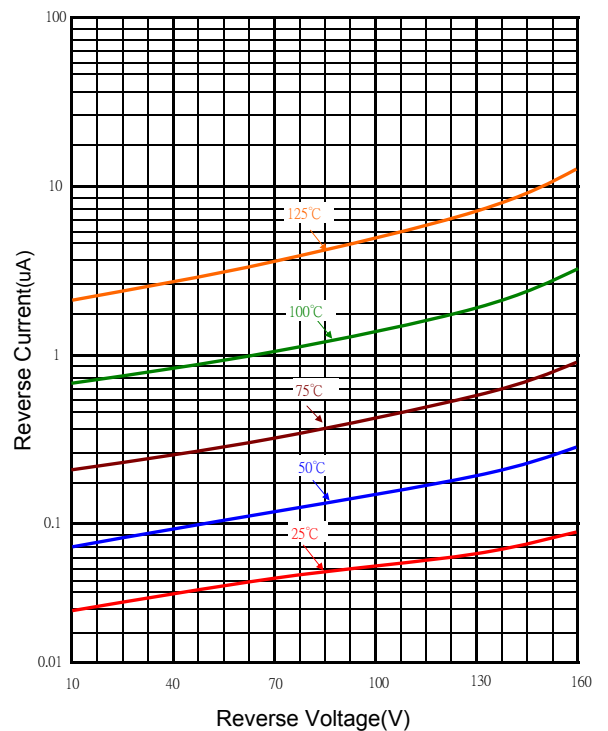
Typical Forward Characteristic



Typical Junction Capacitance



Typical Reverse Characteristic



Maximum Non- Repetitive Forward Surge Current

